



Product Change Notification **CN-202208020F**

Issue date: 04 Oct 2022
Effective date: 03 Jan 2023
Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.
For more details please contact your respective Nexperia CSR/AM.



Last phase of assembly and test transfer TSSOP56 package from ATBK to ATXSZ

Change Category

- Wafer
- Fab
- Process
- Wafer
- Fab
- Materials
- Wafer
- Fab
- Location
- Assembly
- Process
- Product Marking
- Mechanical
- Specification
- Packing/Shipping/Labeling
- Test Location
- Test Process
- Test Equipment
- Design
- Errata
- Electrical spec./Test coverage

Details of this change

Last phase of assembly and test transfer product types in TSSOP56 package from ATBK (NXP Semiconductors, Plant Bangkok Thailand) to ATXSZ (ATX Semiconductors Suzhou, China)

- No change in wafer fab process or fab location
- No change in die (same electrical distribution)
- No change in datasheet and test limits
- No change in form, fit, function, quality or reliability anticipated
- Replace Au (gold) wire with Cu (copper) wire in bonding process

Qualification in accordance to the Automotive Electronics Council:

- AEC-Q100-rev. H Stress Test Qualification for Integrated Circuits
- AEC-Q006-rev. A Qualification requirements for Cu-wire interconnection

SQR_CN-202208020F.pdf: https://qcm.nexperia.com/Document/DOC-544650/SQR_CN-202208020F.pdf

Why do we implement this change?

- Last phase of transfer TSSOP56 products into ATXSZ

Identification of affected products

- The traceability is given by the assembly location indicator suffix which is indicated on the product topside marking and on the reel and box label, see remarks

Management summary

Last phase of assembly and test transfer product types in TSSOP56 package from ATBK (NXP Semiconductors, Plant Bangkok Thailand) to ATXSZ (Suzhou, China)

Product availability

Production

Planned first shipment: 04 Jan 2023

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Change in ordering code 12NC (only the 3NC ending) for some products in the TSSOP56 package. See the PCN product type list / affected 12NC's. All criteria and qualification requirements have been met to achieve moisture sensitivity MSL "1". As a result of this improvement the new TSSOP56 package in ATXSZ will not require dry pack

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 03 Nov 2022. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Remarks

Assembly location indicator suffix on the product topside marking and on the reel and box label: "X"= ATXSZ (Suzhou, China) and "n"= ATBK (NXP Semiconductors Assembly & Test Plant Bangkok, Thailand)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

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SalesItem_name	SalesItem_orderablePartNumber	SalesOrder_customerPartNumber	ProductType_name	BasicType_description	PackageOutlineVersion_description	PackageType_description	SalesItem_state	SalesItem_customerSpecificIndicator	Replacement_SalesItem_orderablePartNumber	Replacement_SalesItem_name	Replacement_ProductType_name	Replacement_BasicType_description	BusinessLine_description
9332440218	74ALV162822DGG		74ALV162822DGG	2.5 V 1.3 V 20-bit bus	SC7384-1	T500P6	RF5	No	74ALV162822DGG,11	9332440218	74ALV162822DGG	2.5 V 1.3 V 20-bit bus-interface D-type 18-Analog & Logic	
9332440818	74ALV162822DGG		74ALV162822DGG	18-bit bus interface D-type	SC7384-1	T500P6	RF5	No	74ALV162822DGG,11	9332440818	74ALV162822DGG	18-bit bus interface D-type flip-flop with 8-Analog & Logic	
9332440918	74ALV162822DGG		74ALV162822DGG	20-bit buffer/line driver	n-SC7384-1	T500P6	RF5	No	74ALV162822DGG,118	9332440918	74ALV162822DGG	20-bit buffer/line driver, non-inverting and Analog & Logic	
9332440918	74ALV162822DGG		74ALV162822DGG	20-bit bus interface D-type	SC7384-1	T500P6	RF5	No	74ALV162822DGG,118	9332440918	74ALV162822DGG	20-bit bus interface D-type flip-flop, push-Analog & Logic	
9332440918	74ALV162822DGG		74ALV162822DGG	20-bit bus interface D-type	SC7384-1	T500P6	RF5	No	74ALV162822DGG,118	9332440918	74ALV162822DGG	20-bit bus interface D-type flip-flop with 8-Analog & Logic	
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9332440918	74ALV162822DGG		74ALV162822DGG	20-bit dual supply transist	SC7384-1	T500P6	RF5	No	74ALV162822DGG,118	9332440918	74ALV162822DGG	20-bit dual supply transist SC7384-1	Analog & Logic
9332440918	74ALV162822DGG		74ALV162822DGG	3.3V 16-bit registered tran	SC7384-1	T500P6	RF5	No	74ALV162822DGG,118	9332440918	74ALV162822DGG	3.3V 16-bit registered transceiver; 3-state Analog & Logic	